## 4V Drive Pch MOS FET

## RSQ025P03

## - Structure

Silicon P-channel MOS FET

## -Features

1) Low On-resistance. ( $120 \mathrm{~m} \Omega$ at 4.5 V )
2) High Power Package. $(P d=1.25 \mathrm{~W})$
3) High speed switching.
4) Low voltage drive. (4V)

## - Applications

DC-DC converter

- External dimensions (Unit : mm)



## -Packaging specifications

| Type | Package | Taping |
| :--- | :--- | :---: |
|  | Code | TR |
|  | Basic ordering unit <br> (pieces) | 3000 |
| RSQ025P03 |  |  |

## - Equivalent circuit



- Absolute maximum ratings ( $\mathrm{Ta}=25^{\circ} \mathrm{C}$ )

| Parameter |  | Symbol | Limits | Unit |
| :---: | :---: | :---: | :---: | :---: |
| Drain-source voltage |  | Voss | -30 | V |
| Gate-source voltage |  | Vass | $\pm 20$ | V |
| Drain current | Continuous | ld | $\pm 2.5$ | A |
|  | Pulsed | lop *1 | $\pm 10$ | A |
| Source current (Body diode) | Continuous | Is | -1 | A |
|  | Pulsed | Isp *1 | -4 | A |
| Total power dissipation |  | Pd *2 | 1.25 | W |
| Channel temperature |  | Tch | 150 | ${ }^{\circ} \mathrm{C}$ |
| Range of Storage temperature |  | Tstg | -55 to +150 | ${ }^{\circ} \mathrm{C}$ |

*1 Pw $\leq 10$ us, Duty cycle $\leq 1 \%$
*2 Mounted on a ceramic board
-Thermal resistance

| Parameter | Symbol | Limits | Unit |
| :---: | :---: | :---: | :---: |
| Channel to ambient | Rth(ch-a) | 100 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |

[^0]Transistor

- Electrical characteristics $\left(\mathrm{Ta}=25^{\circ} \mathrm{C}\right)$

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Gate-source leakage | Igss | - | - | $\pm 10$ | $\mu \mathrm{A}$ | VGS $= \pm 20 \mathrm{~V}, \mathrm{Vds}=0 \mathrm{~V}$ |
| Drain-source breakdown voltage | $V_{\text {(BR) }}$ DSs | -30 | - | - | V | $\mathrm{ID}=-1 \mathrm{~mA}, \mathrm{VGS}=0 \mathrm{~V}$ |
| Zero gate voltage drain current | Idss | - | - | -1 | $\mu \mathrm{A}$ | $\mathrm{V} \mathrm{DS}=-30 \mathrm{~V}, \mathrm{VGS}=0 \mathrm{~V}$ |
| Gate threshold voltage | VGS(th) | -1.0 | - | -2.5 | V | VDS $=-10 \mathrm{~V}, \mathrm{ID}=-1 \mathrm{~mA}$ |
| Static drain-source on-state resistance | RDs(on) ${ }^{*}$ | - | 80 | 110 | $\mathrm{m} \Omega$ | $\mathrm{ld}=-2.5 \mathrm{~A}, \mathrm{VGS}=-10 \mathrm{~V}$ |
|  |  | - | 120 | 165 | $\mathrm{m} \Omega$ | $\mathrm{ld}=-2.5 \mathrm{~A}, \mathrm{VGS}=-4.5 \mathrm{~V}$ |
|  |  | - | 145 | 200 | $\mathrm{m} \Omega$ | $\mathrm{ld}=-1.25 \mathrm{~A}, \mathrm{VGS}=-4.0 \mathrm{~V}$ |
| Foward transfer admittance | $\left\|\mathrm{Y}_{\text {fs }}\right\|^{*}$ | 1.2 | - | - | S | V DS $=-10 \mathrm{~V}, \mathrm{ld}=-1.25 \mathrm{~A}$ |
| Input capacitance | Ciss | - | 320 | - | pF | $\begin{aligned} & \mathrm{VDS}=-10 \mathrm{~V}, \mathrm{VGS}=0 \mathrm{~V} \\ & \mathrm{f}=1 \mathrm{MHz} \end{aligned}$ |
| Output capacitance | Coss | - | 85 | - | pF |  |
| Reverse transfer capacitance | Crss | - | 60 | - | pF |  |
| Turn-on delay time | td(on) * | - | 8 | - | ns | $\begin{aligned} & \mathrm{ld}=-1.25 \mathrm{~A} \\ & \mathrm{~V} D \mathrm{O}=-15 \mathrm{~V} \\ & \mathrm{~V} G S=-10 \mathrm{~V} \\ & \mathrm{RL}=12 \Omega \\ & \mathrm{RG}=10 \Omega \end{aligned}$ |
| Rise time | $\mathrm{tr}^{*}$ | - | 11 | - | ns |  |
| Turn-off delay time | td(off) * | - | 33 | - | ns |  |
| Fall time | $\mathrm{tf}^{*}$ | - | 7 | - | ns |  |
| Total gate charge | Qg | - | 4.4 | - | nC | $\begin{aligned} & \mathrm{VDD} \fallingdotseq-15 \mathrm{~V} \\ & \mathrm{VGS}=-5 \mathrm{~V} \\ & \mathrm{ID}=-2.5 \mathrm{~A} \end{aligned}$ |
| Gate-source charge | Qgs | - | 1.0 | - | nC |  |
| Gate-drain charge | Qgd | - | 1.4 | - | nC |  |

- Body diode characteristics (Source-drain) ( $\mathrm{Ta}=25^{\circ} \mathrm{C}$ )

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: |
| Forward voltage | Vsd | - | - | -1.2 | V | $\mathrm{Is}=-0.9 \mathrm{~A}, \mathrm{VGs}=0 \mathrm{~V}$ |

## -Electrical characteristic curves



Gate-Source Voltage : - $\mathrm{VGs}[\mathrm{V}]$
Fig. 1 Typical Transfer Characteristics


Fig. 4 Static Drain-Source On-State Resistancevs.Drain-Current


Fig. 2 Static Drain-Source On-State Resistancevs.Drain Current


Fig. 5 Static Drain-Source On-State Resistance vs.Drain-Current


Fig. 3 Static Drain-Source On-State Resistance vs.Drain Current


Fig. 6 Reverse Drain Current Source-Drain Voltage




## - Measurement circuits



Fig. 10 Switching Time Measurement Circuit


Fig. 12 Gate Charge Measurement Circuit


Fig. 11 Switching Waveforms


Fig. 13 Gate Charge Waveforms

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[^0]:    * Mounted on a ceramic board.

